

Attorney Dock t No. 50626.53

DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled IMPROVED BALL GRID ARRAY PACKAGE AND PROCESS FOR MANUFACTURING SAME the specification of which is attached hereto unless the following box is checked:

was filed on August 20, 2003 as United States Application Number 10/643,961 or PCT International

Application Number	and w	as amended on	(if applicable).
I hereby state that I have review claims, as amended by any am			ied specification, including the
I acknowledge the duty to disci	ose information which is	s material to patentability as d	efined in 37 CFR § 1.56.
I hereby claim foreign priority be patent or inventor's certificate, country other than the United Sor inventor's certificate, or PCT priority is claimed.	or § 365(a) of any PCT States, listed below and	International application which have also identified below any	n designated at least one y foreign application for patent
Prior Foreign Application(s)		Priority Date	Priority Claimed
(Number)	(Country) (PCT)	(Day/Month/Year Filed	Yes No ——
Prior Foreign Application(s)		Priority Date	Priority Claimed
(Number)	(Country) (PCT)	(Day/Month/Year Filed	Yes No — —
I hereby claim the benefit unde	г 35 U.S.C. § 119(e) of	any United States provisional	application(s) listed below.
Application Number)		(Filing Date)	
(Application Number)		(Filing Date)	

I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose information which is material to

patentability as defined in 37 CFR § 1.56 which became available betwe in the filing date of the prior application and the national or PCT International filing date of this application. December 20, 2002 pending (Application Number) (Filing Date) (Status-patented, pending, abandoned) July 19, 2002 10/197.832 (Application Number) (Status – patented, pending, abandoned) (Filing Date) I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith: Joseph R. Keating, Reg. No. 37,368 Address all correspondence to: Joseph R. Keating, Esq. Keating & Bennett LLP 10400 Eaton Place, Suite 312 Fairfax, VA 22030 (703) 385-5200 I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon. Full name of first inventor (given name, family name) Chun Ho FAN Inventor's signature Date Residence Flat E. 27/F. Blk 3. Lido Garden, Sham Tseng, N.T., Hong Kong, Citizenship British National <u>Overseas</u> Post Office Address Same as above Full name of second inventor (biven name, family name) Wing Keung LAM Inventor's signature Residence Rm. 2614, Lok Yan House\ Tsz Wan Shan, Kowloon, Hong Kong, Citizenship __ Chinese Post Office Address ___ Same as above Full name of third inventor (given name, family name) Ming Wang SZE Inventor's signature Residence Flt. F. 15/F. Cheong Ning Building, Jeven Cheong Center, 202-216 Sai Lau Kok Road, Tsuen Wan, New Territories. Hong Kong Citizenship

Chinese

Post Office Address Same as above

Full name of fourth inventor (given name, family name) Sadak Thamby LABEEB				
Inventor's signature Themy Date 10-06-03				
Residence Flat F, 14/F, Block 21, Riviera Garden, Tsuen Wan, N.T., Hong Kong, Citizenship Indian				
Post Office Address Same as above				
Full name of fifth inventor (given name, family name) Neil McLELLAN				
rui flame of fillit inventor (given hame, family flame) Nei Michaelle				
Inventor's signatureDate				
Residence 110 Woodranch Cr., Danville, California, U.S.A. 94506 Citizenship U.S.A.				
Post Office Address Same as above				
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Full name of sixth inventor (given name, family name) Mohan KIRLOSKAR				
inventor's signature Hohan Kyroman Date 8 oct '03				
Residence 7712 Oak Meadow Court. Compertino, California, U.S.A. 95014 Citizenship U.S.A.				
Post Office Address Same as above				

Full name of fourth inventor (given name, family name) Sadak Thamby LABEEB				
Inventor's signature Date				
Residence Flat F, 14/F, Block 21, Riviera Garden, Tsuen Wan, N.T., Hong Kong Citizenship Indian				
Post Office Address Same as above				
Full name of fifth inventor (given name, family name) Neil McLELLAN				
Full name of fifth inventor (given name, family name) Neil McLELLAN Inventor's signature Date // 20 03				
Residence 110 Woodranch Cr., Danville, California, U.S.A. 94506 Citizenship U.S.A.				
Post Office Address Same as above				
Full name of sixth inventor (given name, family name) Mohan KIRLOSKAR				
Inventor's signature Date				
Residence 7712 Oak Meadow Court, Coopertino, California, U.S.A. 95014 Citizenship U.S.A.				
Post Office Address Same as above				